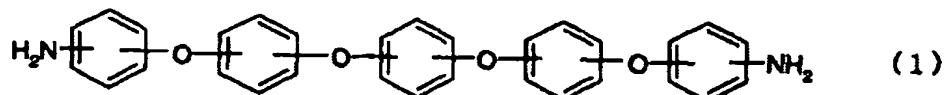
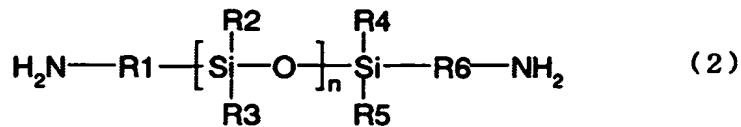


CLAIMS

1. An adhesive resin comprising a polyimide resin obtained by reacting a diamine component containing a diamine represented by the following formula (1) as an essential component with a tetracarboxylic dianhydride component,

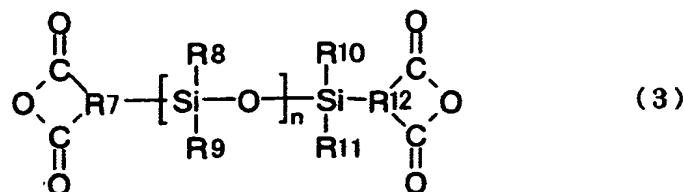


wherein the polyimide comprises a diamine represented by the following formula (2) as a diamine component,



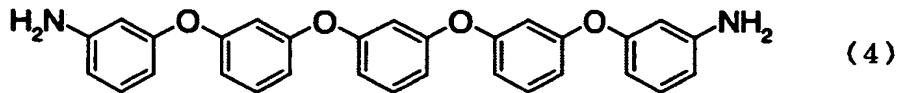
(wherein R1 and R6 are divalent aliphatic groups having 1 to 4 carbon atoms or aromatic groups; R2 to R5 are monovalent aliphatic groups or aromatic groups; and n is an integer of 0 to 20)

and/or a tetracarboxylic dianhydride represented by the following formula (3) as the tetracarboxylic dianhydride component,



(wherein R7 and R12 are trivalent aliphatic groups or aromatic groups; R8 to R11 are monovalent aliphatic groups or aromatic groups; the carbon skeleton of the acid anhydride structure is a 5- or 6-membered ring; and n is an integer of 0 to 20).

2. The adhesive resin according to Claim 1, wherein the diamine represented by the formula (1) comprises a diamine represented by the following formula (4).



3. The adhesive resin according to Claim 1 or 2 comprising a thermosetting resin except a polyimide resin.

4. The adhesive resin according to Claim 3, wherein the thermosetting resin comprises an epoxy resin, and the adhesive resin further comprises an epoxy resin-curing agent.

5. The adhesive resin according to any one of Claims 1 to 4 comprising inorganic filler.

6. A film adhesive comprising the adhesive resin according to any one of Claims 1 to 5.

7. A semiconductor device wherein a semiconductor element is attached to a support by the film adhesive according to Claim 6.